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PARK et al.(10) **Pub. No.: US 2022/0386479 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **BATCH JOINING TYPE MULTI-LAYER
PRINTED CIRCUIT BOARD AND
MANUFACTURING METHOD OF THE SAME****Publication Classification**

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(57) **ABSTRACT**

A multilayer circuit board including a ceramic substrate part and a unit circuit board coupled to one surface of the ceramic substrate part. The unit circuit board includes an insulating layer with a circuit pattern formed on one side, an adhesive layer adhered to another surface of the insulating layer, a via hole passing through the insulating layer and the adhesive layer and connected to one surface of the circuit pattern, and conductive paste filled in the via hole.

A manufacturing method including batch bonding a circuit board part, which includes a plurality of unit circuit boards, and a ceramic substrate part, wherein each unit circuit board includes providing an insulating layer having a circuit layer, forming an adhesive layer on the insulating layer, forming a circuit pattern, forming a via hole in the insulating and adhesive layers, and filling the via hole with conductive paste.

